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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Active
Core Processor	HCS12
Core Size	16-Bit
Speed	25MHz
Connectivity	CANbus, I ² C, SCI, SPI
Peripherals	PWM, WDT
Number of I/O	59
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	12K x 8
Voltage - Supply (Vcc/Vdd)	2.35V ~ 5.25V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	80-QFP
Supplier Device Package	80-QFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9s12dg256mfue

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong



MC9S12D-Family

Product Brief

16-Bit Microcontroller

Designed for automotive multiplexing applications, members of the MC9S12D-Family of 16 bit Flash-based microcontrollers are fully pin compatible and enable users to choose between different memory and peripheral options for scalable designs. All MC9S12D-Family members are composed of standard on-chip peripherals including a 16-bit central processing unit (CPU12), up to 512K bytes of Flash EEPROM, 14K bytes of RAM, 4K bytes of EEPROM, two asynchronous serial communications interfaces (SCI), three serial peripheral interfaces (SPI), IIC-bus, an enhanced capture timer (ECT), two 8-channel 10-bit analog-to-digital converters (ADC), an eight-channel pulse-width modulator (PWM), J1850 interface and up to five CAN 2.0 A, B software compatible modules (MSCAN12). System resource mapping, clock generation, interrupt control and bus interfacing are managed by the system integration module (SIM). The MC9S12D-Family has full 16-bit data paths throughout, however, the external bus can operate in an 8-bit narrow mode so single 8-bit wide memory can be interfaced for lower cost systems. The inclusion of a PLL circuit allows power consumption and performance to be adjusted to suit operational requirements. In addition to the I/O ports available in each module, up to 22 I/O ports are available with interrupt capability allowing Wake-Up from STOP or WAIT mode.

Features

NOTE

Not all features listed here are available in all configurations.

Additional information about D and B family inter-operability is given in:

EB386 "HCS12 D-Family Compatibility Considerations" and

EB388 "Using the HCS12 D-Family as a development platform for the HCS12 B family"

• 16-bit CPU12

- Upward compatible with M68HC11 instruction set
- Interrupt stacking and programmer's model identical to M68HC11
- HCS12 Instruction queue
- Enhanced indexed addressing

Multiplexed bus

- Single chip or expanded
- 16 address/16 data wide or 16 address/8 data narrow modes
- External address space 1MByte for Data and Program space (112 pin package only)

Wake-up interrupt inputs depending on the package option

- 8-bit port H
- 2-bit port J1:0
- 2-bit port J7:6 shared with IIC, CAN4 and CAN0 module
- 8-bit port P shared with PWM or SPI1,2

Memory options

- 32K, 64K, 128K, 256K, 512K Byte Flash EEPROM
- 1K, 2K, 4K Byte EEPROM
- 2K, 4K, 8K, 12K, 14K Byte RAM



Analog-to-Digital Converters

- One or two 8-channel modules with 10-bit resolution depending on the package option
- External conversion trigger capability

Up to five 1M bit per second, CAN 2.0 A, B software compatible modules

- Five receive and three transmit buffers
- Flexible identifier filter programmable as 2 x 32 bit, 4 x 16 bit or 8 x 8 bit
- Four separate interrupt channels for Receive, Transmit, Error and Wake-up
- Low-pass filter wake-up function in STOP mode
- Loop-back for self test operation

• Enhanced Capture Timer (ECT)

- 16-bit main counter with 7-bit prescaler
- 8 programmable input capture or output compare channels; 4 of the 8 input captures with buffer
- Input capture filters and buffers, three successive captures on four channels, or two captures on four channels with a capture/compare selectable on the remaining four
- Four 8-bit or two 16-bit pulse accumulators
- 16-bit modulus down-counter with 4-bit prescaler
- Four user-selectable delay counters for signal filtering

• 8 PWM channels with programmable period and duty cycle (7 channels on 80 Pin Packages)

- 8-bit, 8-channel or 16-bit, 4-channel
- Separate control for each pulse width and duty cycle
- Center- or left-aligned outputs
- Programmable clock select logic with a wide range of frequencies

Serial interfaces

- Two asynchronous serial communications interfaces (SCI)
- Up to three synchronous serial peripheral interfaces (SPI)
- IIC

• SAE J1850 Compatible Module (BDLC)

- 10.4 kbps Variable Pulse Width format
- Byte level receive and transmit
- 4x receive mode supported

• SIM (System Integration Module)

- CRG (windowed COP watchdog, real time interrupt, clock monitor, clock generation and reset)
- MEBI (multiplexed external bus interface)
- INT (interrupt control)

Clock generation

- Phase-locked loop clock frequency multiplier
- Limp home mode in absence of external clock
- Clock Monitor
- Low power 0.5 to 16 MHz crystal oscillator reference clock

Operating frequency for ambient temperatures T_A -40°C <= T_A <= 125°C

- 50MHz equivalent to 25MHz Bus Speed for single chip 40MHz equivalent to 20MHz Bus Speed in expanded bus modes.
- Internal 5V to 2.5V Regulator

112-Pin LQFP or 80-Pin QFP package

- I/O lines with 5V input and drive capability
- 5V A/D converter inputs and 5V I/O
- 2.5V logic supply

Development support

- Single-wire background debug[™] mode (BDM)
- On-chip hardware breakpoints



Table 1 List of MC9S12D-Family members

Flash	RAM	EEPROM	Package	Device	CAN	J1850	SCI	SPI	IIC	A/D	PWM	I/O
512K		4K	112LQFP	DP512	5	1	2	3	1	2/16	8	91
	14K			DT512	3	0	2	3	1	2/16	8	91
				DJ512	2	1	2	3	1	2/16	8	91
256K 1	12K	4K	112LQFP	DT256	3	0	2	3	1	2/16	8	91
				DJ256	2	1	2	3	1	2/16	8	91
				DG256	2	0	2	3	1	2/16	8	91
			80QFP	DJ256	2	1	2	3	1	1/8	7	59
				DG256	2	0	2	3	1	1/8	7	59
		2K	112LQFP	DT128	3	0	2	2	1	2/16	8	91
				DJ128	2	1	2	2	1	2/16	8	91
128K	8K			DG128	2	0	2	2	1	2/16	8	91
			80QFP	DJ128	2	1	2	2	1	1/8	7	59
				DG128	2	0	2	2	1	1/8	7	59
64K	4K	1K	112LQFP	DJ64	1	1	2	1	1	2/16	8	91
				D64	1	0	2	1	1	2/16	8	91
			80QFP	DJ64	1	1	2	1	1	1/8	7	59
				D64	1	0	2	1	1	1/8	7	59
32K	2K	1K	80QFP	D32	1	0	2	1	0	1/8	7	59

• Pin out explanations:

- A/D is the number of modules/total number of A/D channels.
- I/O is the sum of ports capable to act as digital input or output.
 - 112 Pin Packages:

Port A = 8, B = 8, E = 6 + 2 input only, H = 8, J = 4, K = 7, M = 8, P = 8, S = 8, T = 8, PAD = 16 input only.

22 inputs provide Interrupt capability (H =8, P= 8, J = 4, IRQ, XIRQ)

80 Pin Packages:

Port A = 8, B = 8, E = 6 + 2 input only, J = 2, M = 6, P = 7, S = 4, T = 8, PAD = 8 input only. 11 inputs provide Interrupt capability (P= 7, J = 2, IRQ, XIRQ)

- CAN0 pins are shared between J1850 pins.
- CANO can be routed under software control from PM1:0 to pins PM3:2 or PM5:4 or PJ7:6.
- CAN4 pins are shared between IIC pins.
- CAN4 can be routed under software control from PJ7:6 to pins PM5:4 or PM7:6.
- Versions with 4 CAN modules will have CAN0, CAN1, CAN2 and CAN4.
- Versions with 3 CANs modules will have CAN0, CAN1 and CAN4.
- Versions with 2 CAN modules will have CAN0 and CAN4.
- Versions with one CAN module will have CAN0.
- Versions with 2 SPI modules will have SPI0 and SPI1.
- Versions with 1 SPI will have SPI0.
- SPI0 can be routed to either Ports PS7:4 or PM5:2.
- SPI2 pins are shared with PWM7:4; In 112 pin versions SPI2 can be routed under software control to PH7:4. In 80 pin packages SS-signal of SPI2 is not bonded out!

NOTE

CAN and SPI routing features are not available on the 1st PC9S12DP256 mask set 0K36N!



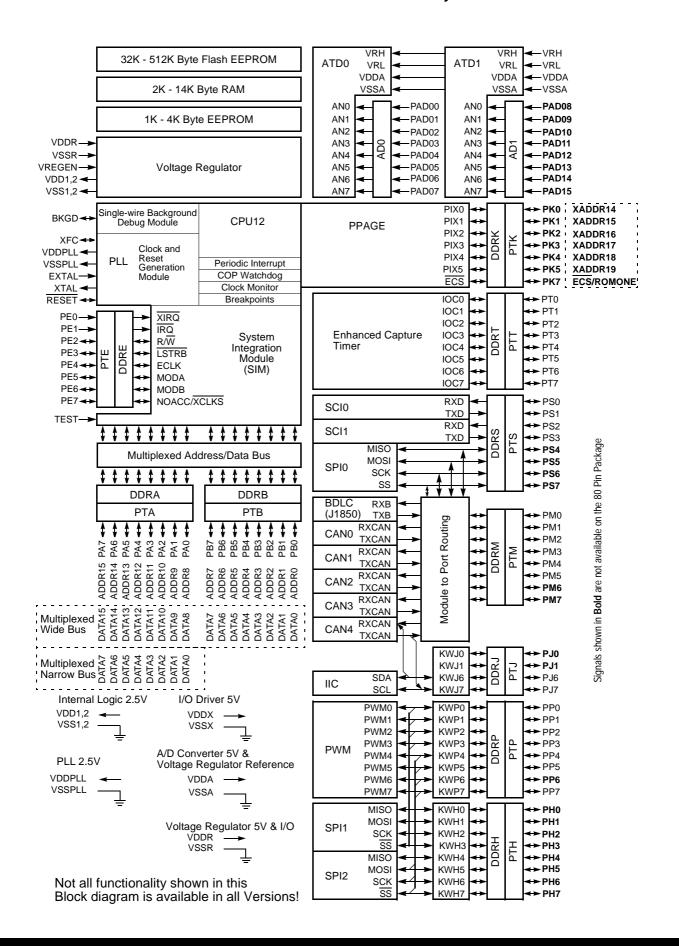
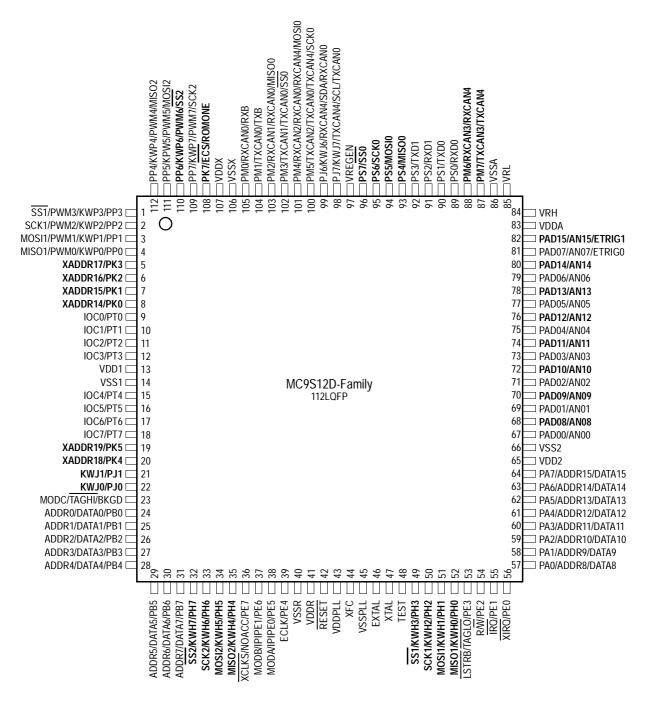




Figure 1 Pin assignments 112 LQFP for MC9S12D-Family



Signals shown in **Bold** are not available on the 80 Pin Package



Figure 2 Pin Assignments in 80 QFP for MC9S12D-Family

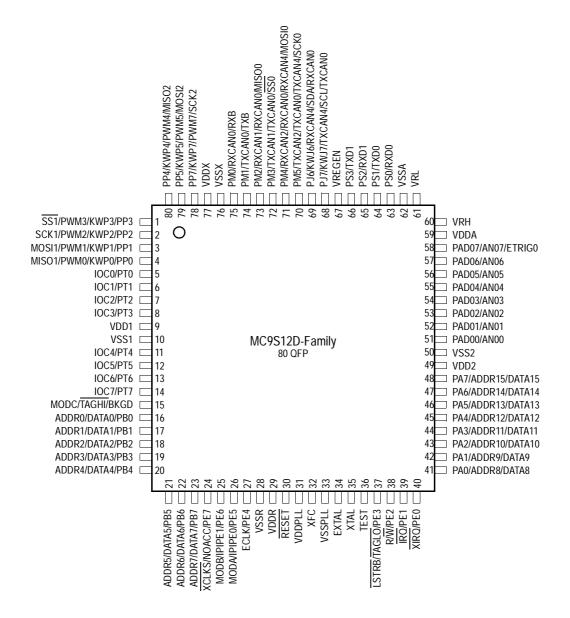
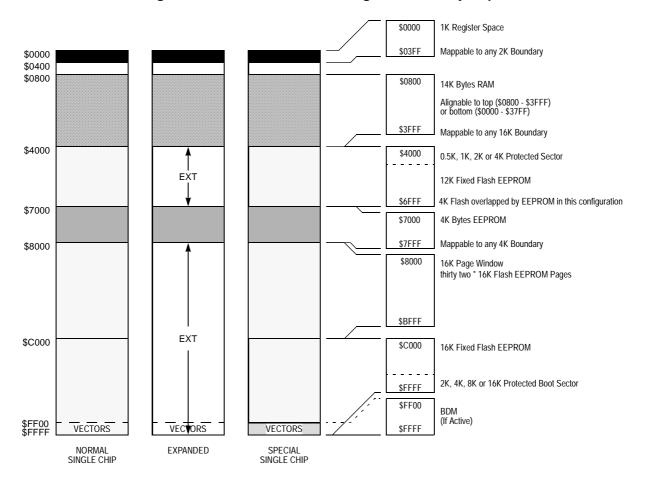




Figure 3 MC9S12Dx512 User Configurable Memory Map



The figure shows a useful map, which is not the map out of reset. After reset the map is:

\$0000 - \$03FF: Register Space \$0800 - \$3FFF: 14K RAM \$0000 - \$0FFF: 4K EEPROM (1k \$0400 - \$07FF visible, \$0000 - \$03FF and \$0800 - \$0FFF are not visible) Various possibilities to make more of the EEPROM fully visible are available, one of them is shown above



Figure 4 MC9S12Dx256 User Configurable Memory Map

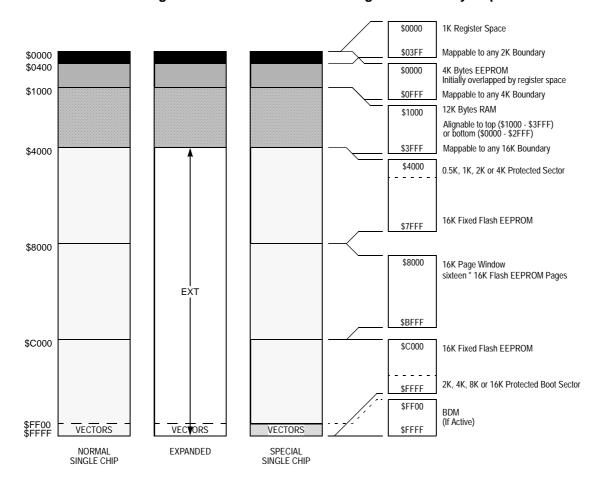
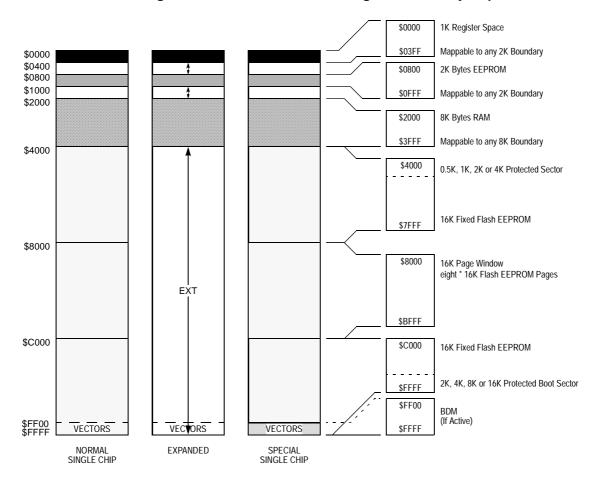




Figure 5 MC9S12Dx128 User Configurable Memory Map

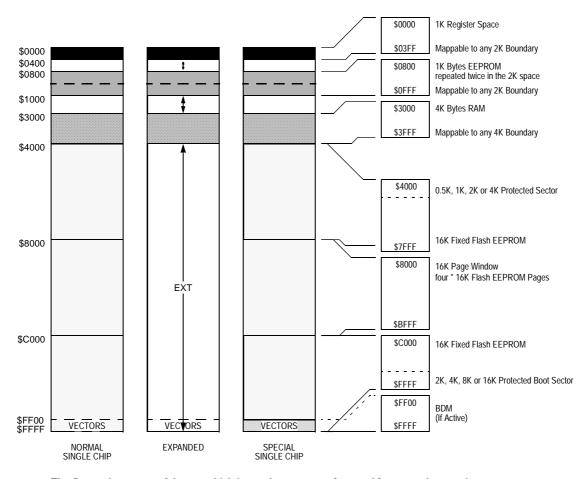


The figure shows a useful map, which is not the map out of reset. After reset the map is:

\$0000 - \$03FF: Register Space \$0000 - \$1FFF: 8K RAM \$0000 - \$07FF: 1K EEPROM (not visible)



Figure 6 MC9S12Dx64 User Configurable Memory Map

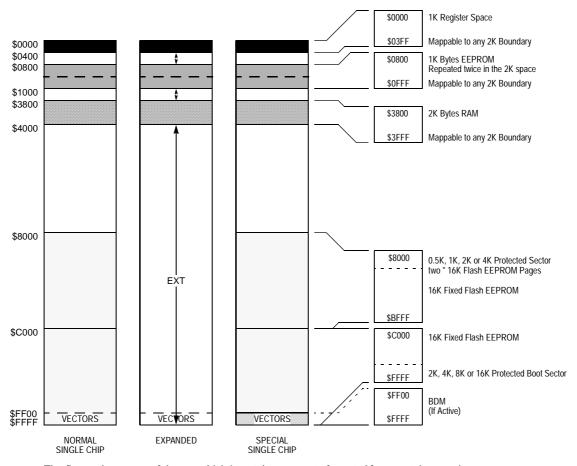


The figure shows a useful map, which is not the map out of reset. After reset the map is:

\$0000 - \$03FF: Register Space \$0000 - \$0FFF: 4K RAM \$0000 - \$07FF: 1K EEPROM (not visible)



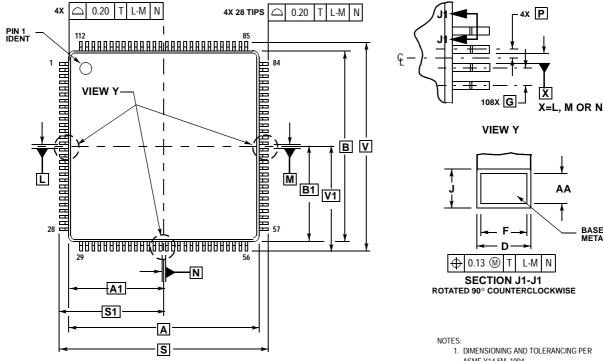
Figure 7 MC9S12Dx32 User Configurable Memory Map

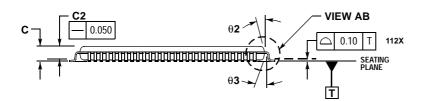


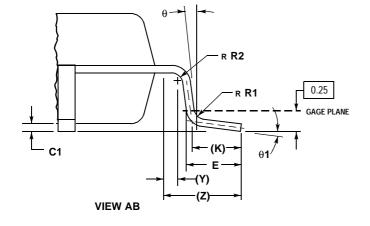
The figure shows a useful map, which is not the map out of reset. After reset the map is:

\$0000 - \$03FF: Register Space \$0800 - \$0FFF: 2K RAM \$0000 - \$07FF: 1K EEPROM (not visible)









- ASME Y14.5M, 1994.
- 2. DIMENSIONS IN MILLIMETERS.
- 3. DATUMS L, M AND N TO BE DETERMINED AT

BASE METAL

- SEATING PLANE, DATUM T.
 4. DIMENSIONS S AND V TO BE DETERMINED AT SEATING PLANE, DATUM T.
- 5. DIMENSIONS A AND B DO NOT INCLUDE MOLD PROTRUSION. ALLOWABLE
 PROTRUSION IS 0.25 PER SIDE. DIMENSIONS A AND B INCLUDE MOLD MISMATCH.
- 6. DIMENSION D DOES NOT INCLUDE DAMBAR

		IETERO					
	MILLIMETERS						
DIM	MIN	MAX					
Α	20.000 BSC						
A1	10.000 BSC						
В	20.000 BSC						
B1	10.000 BSC						
С		1.600					
C1	0.050	0.150					
C2	1.350	1.450					
D	0.270	0.370					
Ε	0.450	0.750					
F	0.270	0.330					
G	0.650 BSC						
J	0.090	0.170					
K	0.500 REF						
P	0.325 BSC						
R1	0.100	0.200					
R2	0.100	0.200					
S	22.000 BSC						
S1	11.000 BSC						
٧	22.000 BSC						
V1	11.000 BSC						
Υ	0.250 REF						
Z	1.000 REF						
AA	0.090	0.160					
θ	0°	ŏ					
θ1	3 °	7 °					
θ2	11 °	13 °					
θ3	11 °	13 °					

Figure 8 112-pin LQFP Mechanical Dimensions (case no. 987)



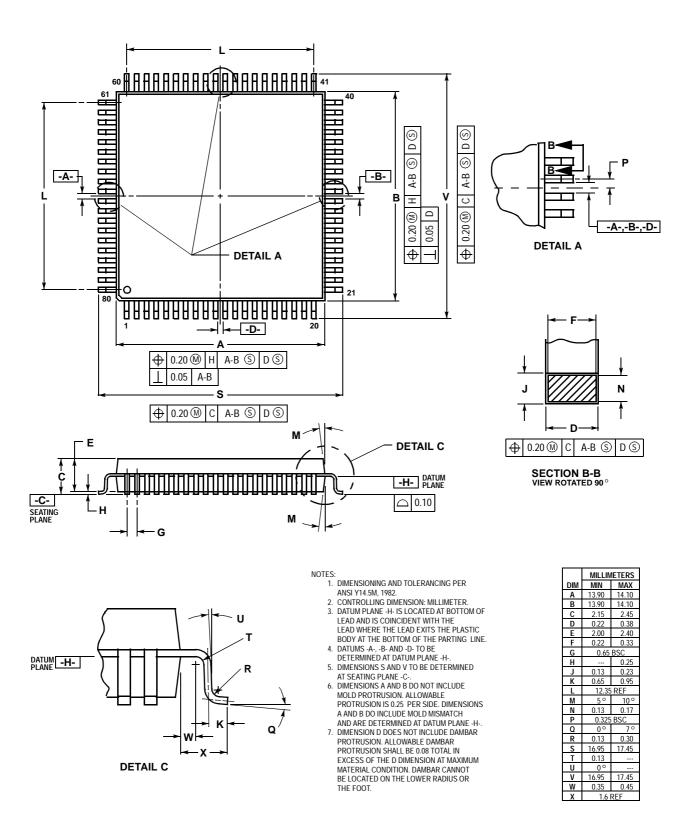


Figure 9 80-pin QFP Mechanical Dimensions (case no. 841B)



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